MAY 1. 0 2004 MAY 1. 0 2004 TRADE Client Ref. No.: 020964-003900US

Title of Invention

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76)

SEMICONDUCTOR DEVICE PACKAGE DIEPAD HAVING FEATURES FORMED

	BY ELECTROP	PLATING		
As the below named inventor(s), I/we declare that:				
This declaration is directed	d to:			
С	The attach	ned application, or		
Σ	Application	n No. 10/751,265, filed o	n January 2,	2004,
	as am	ended on (if applic	able);	
I/we believe that I/we am/are the original and first inventor(s) of the subject matter which is claimed and for which a patent is sought;				
I/we have reviewed and understand the contents of the above-identified application, including the claims, as amended by any amendment specifically referred to above;				
I/we acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me/us to be material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT International filing date of the continuation-in-part application.				
All statements made herein of my/our own knowledge are true, all statements made herein on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like are punishable by fine or imprisonment, or both, under 18 U.S.C. 1001, and may jeopardize the validity of the application or any patent issuing thereon.				
FULL NAME OF INVENTOR(S)				
Inventor 1 Hamza			Date:	Ani/ 23 20014
Signature:			Citizen of:	United States
Inventor 2 Anthony	Chia		Date:	A1R121,04
Signature:	fuge		_ Citizen of:	Singapore
Inventor 3 Seishi F	ujimaki		Date:	4/23/2004
Signature:	光正丈	_	_ Citizen of:	Japan
Inventor 4 Xiaogua	ing Zeng		Date:	April 22,04
Signature: Zany C	inozny		Citizen of:	Peoples Republic of China
Additional inventors are being named on additional form(s) attached hereto.				

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MAY 1	2004
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POWER OF ATTORNEY and CORRESPONDENCE ADDRESS INDICATION FORM

Application Number	10/751,265		
Filing Date	January 2, 2004		
First Named Inventor	Yilmaz, Hamza		
Title	SEMICONDUCTOR DEVICE PACKAGE DIEPAD HAVING FEATURES FORMED BY ELECTROPLATING		
Art Unit	Unassigned		
Examiner Name	Unassigned		
Attorney Docket Number	020964-003900US		

I hereby a	ppoint:					
Practitioners associated with the Customer Number		20350				
OR		•	L	-		
Practi	tioner(s) na	med below:				
		Name .		Registration	Number	
						(Y.)
		or agent(s) to prosecute the application office connected therewith.	n identified	d above, and to tr	ansact all busine	ss in the United States
Please reco	ognize or cl	nange the correspondence address for	the above	e-identified applic	ation to:	
	lress assoc	iated with the above-mentioned Custo	mer Numb	er:		
O	₹					
☐ The add	tress assoc	ciated with Customer Number:				
OR .						
☐ Firm <i>or</i> Individu	ial Name					
Address						
Address	,					
City	·		State		ZIP	
Country						
Telephone			Fax			
I am the: ☐ Applicant/Inventor. ☐ Assignee of record of the entire interest. See 37 CFR 3.71.						
Staten	nerit under	37 CFR 3.73(b) is enclosed. (Form PT	i			
		SIGNATURE of Applic	ant or As	signee of Recor	·d	•
Name RICHARA J. KULL						
Signature Signature						
Date	was of all the	4/24/2004		Telephone	415-806	
NOTE: Signatures of all the inventors or assignees of record of the entire interest or their representative(s) are required. Submit multiple forms if more than one signature is required, see below.						
☐ *Total o	<u> </u>	forms are submitted.				



STATEM	ENT UNDER 37 CFR 3.73(b)			
Applicant/Patent Owner: HAMZA YILMAZ et al.				
Application No /Patent No : 10/751 265	Filed/Issue Date: January 2, 2004			
	KAGE DIEPAD HAVING FEATURES FORMED BY			
ELECTROPLATING	WASH DIE AD HAVING FLATUNES FORWIED DE			
GEM Services, Inc. , a	Corporation			
(Name of Assignee) (Type of Assignee, e.g., corporation, partnership, university, government ager				
states that it is:				
1. the assignee of the entire right, title, and interest; or				
 an assignee of less than the entire right, title and interest. The extent (by, percentage) of its ownership interest is% 				
in the patent application/patent identified above	by virtue of either:			
	patent application/patent identified above. The assignment was Trademark Office at Reel, Frame, or for which a copy			
OR				
B. A chain of title from the inventor(s), of the shown below:	patent application/patent identified above, to the current assignee as			
1. From:	To :			
The document was recorded in the U Reel, Frame, or for whi	Inited States Patent and Trademark Office at			
, i fame, or for will				
2. From:				
Reel, Frame, or for whi	Inited States Patent and Trademark Office at character character character character.			
3. From:	To :			
The document was recorded in the U	Inited States Patent and Trademark Office at			
Reel, Frame, or for whi	ch a copy thereof is attached.			
Additional documents in the chain of	title are listed on a supplemental sheet.			
☐ Copies of assignments or other documents in				
	signment document or a true copy of the original document) accordance with 37 CFR Part 3, if the assignment is to be IPEP 302.8]			
The undersigned (whose title is supplied below)	is authorized to act on behalf of the assignee.			
424/2004	RICHARD J. KHLLE			
Date	Tured or printed name			
715-806-6777 Telephone number	Signature			
receptione number	PRESIDENT É CED			
	Title			



Attorney Docket No.: 020964-003900US

ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, Hamza Yilmaz of 20755 Trinity Avenue, Saratoga, CA 95057; Anthony Chia of Box 415, #7-105 Bedok North Ave. 2, Singapore, 460415 Singapore; Seishi Fujimaki of 4-7C, JinQiao Garden TongZhuAnBan Road, Shanghai, Peoples Republic of China; Xiaoguang Zeng of Room: 802, No:31, Lane 1661 Changnin Road, Shanghai, Peoples Republic of China, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention:

SEMICONDUCTOR DEVICE PACKAGE DIEPAD

HAVING FEATURES FORMED BY ELECTROPLATING

Filing Date:

60193333 v1

January 2, 2004

Application No.:

10/751,265; and

WHEREAS, **GEM Services, Inc.**, a corporation of United States, located at 1550 Sheffield Avenue, San Jose, CA 95125, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Dated: MRIL 22, 04

Dated: MIZZOU4

Hamza Yilmaz

Anthony Chia

Dated: MIZZOU4

Dated: MIZZOU4

Anthony Chia

Dated: MIZZOU4

Anthony Chia

Seishi Fujimaki

Dated: MIZZOU4

Xiaoguang Zeng